

Aluminum Microelectronic Packages

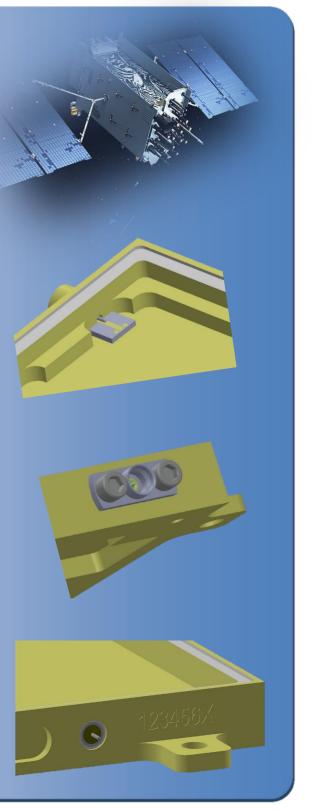
CPS Technologies has the capability to manufacture machined aluminum microelectronic packages for defense, aerospace, and other applications.

Product features include the following capabilities...

- Soldered-in glass terminals and/or ceramic interconnects; internally manufactured or customer sourced.
 - RF terminals (SMA, SSMP, GPO & GPPO)
 - DC terminals
 - Ceramic thin-film networks (TFNs)
- Solving thermal challenges utilizing Aluminum Silicon Carbide (AlSiC).
- Brazed-in mechanical features including mounting studs.
- Value-added hardware installation including helical insert installation.
- Selectively plated or secondary machined surfaces.
- Engraving for part numbers and serialization.

Other Products...

- Machined housing in ASTM F-15
- Plug-ins
- Power packages









CPS Technologies Certified to ISO 9001:2015 Standard

CPS Technologies provides quality assurance testing to MIL-STD 883 and MIL-STD 202; CPS is compliant to DFARS clause 252.225-7014 ALT.1, RoHS and REACH.

CPS Technologies Plating Recourses

- Electroless Nickel per MIL-C-26074, ASTM B-733 and AMS 2404
- Electrolytic Nickel per QQ-N-290 and ASTM B-689
- Gold per ASTM B-488 and MIL-DTL-45204
- Chromate per MIL-DTL-5541

CPS Technologies Test Capabilities

- Air to Air temperature cycle/shock per MIL-STD-883, method 1010
- Steam age/solderability testing per MIL-STD-883, method 2003
- Liquid to Liquid per MIL-STD-883, method 1011
- Lead Fatigue per MIL-STD-883, method 2004
- Hermeticity validation to 1 x 10⁻¹⁰cc/sec of helium per MIL-STD-883, method 1014, condition A4
- Insulation resistance to 10 GΩ at 500 VDC per MIL-STD-883, method 1003
- Salt spray per MIL-STD-883, method 1009
- Compliance to JEDEC and MIL-STD-883



